

REMARKS

This case has been reviewed and analyzed in view of the Official Action dated 20 December 2000. Responsive to the rejections made by the Examiner in the Official Action, Claim 4 has now been canceled from this case and Claims 1-3, 5 and 6 have been amended to more clearly clarify the inventive concept of the Applicant.

Prior to a discussion of the Examiner's objections and rejections made in the outstanding Official Action, it is believed that it may be beneficial to briefly review the subject Patent Application system in light of the inventive concept of the Applicant. The subject Patent Application system is directed to a semiconductor packaging structure for packaging a semiconductor element. As shown in Figure 4 of the Drawings, the semiconductor packaging structure includes a substrate 200 having a chip seat 210 formed thereon. Chip 20 is seated on chip seat 210 and is electrically connected to the plurality of outer lead wires 222 by bonding wires 250. Wall 240 is built along the periphery of substrate 200 with liner 230 being positioned between wall 240 and the plurality of outer lead wires 222. A transparent upper cover 260 is mounted on wall 240.

The Examiner has rejected Claim 2 under 35 U.S.C. § 112, first paragraph, as containing subject matter which was not described in the Specification in such a way as to enable one skilled in the art to which it pertains, or with which it is most nearly

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connected, to make and/or use the invention. Specifically, the Examiner objects to the use of “a transparent upper cover is installed on the element” in Claim 2. Claim 2, however, has now been amended to read “...wherein a transparent upper cover is mounted on said wall.” The Specification discloses the transparent cover being mounted on the wall, thus, it is now believed that Claim 2 satisfies the requirements of 35 U.S.C. § 112, first paragraph.

The Examiner has further rejected Claims 1-6 under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly Claim the subject matter which the Applicant regards as the invention. Specifically, the Examiner objects to the limitation “the elements” in Line 11 of Claim 1. Claim 1, however, has now been amended to read “...bonding wires electrically connecting said semiconductor element...”, which has sufficient antecedent basis in Claim 1. It is now believed that Claim 1 satisfies the requirements of 35 U.S.C. § 112, second paragraph. Further, the Examiner rejected Claims 2-6 for the same reason of Claim 1, Claims 2-6 being dependent on Claim 1. With Claim 1 having been amended, it is now believed that Claims 2-6 also satisfy the requirements of 35 U.S.C. § 112, second paragraph.

The Examiner further rejected Claim 4 under 35 U.S.C. § 112, second paragraph, for reciting the group of “BT, FR3x, FR4xx, and FR5xx”. These materials were not

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defined and Claim 4 has now been canceled from this case.

It is now believed that the subject Patent Application has been placed in condition for allowance, and such action is respectfully requested.

Respectfully submitted,

A handwritten signature in cursive script, appearing to read "Morton J. Rosenberg".

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